

Wafer Cleaning System

The Model UH118 Wafer Cleaning System follows in the footsteps of its highly successful sibling, the Model UH117, and provides an optimal solution for cleaning wafers after dicing or scribing. The unit is capable of cleaning 8-inch film frame-mounted wafers. Operation is semiautomatic and fully programmable via a touchscreen LCD panel, further eliminating operator variables.

The system is microprocessor-controlled to assure precise, flexible, uniform, and repeatable cleaning. Like the Model UH117, up to 10 programs with up to 99 different cleaning/rinsing/drying steps of up to 999

seconds maximum can be stored for different processes. However, the Model UH118 boasts programmable brush speed and an electronically adjustable workstage height (with built-in safety interlock) by entering the substrate thickness.

The Model UH118 Wafer Cleaning System provides dual liquid additive capability through independent channels, in addition to the separate DI water channel. For more efficient drying, the unit is equipped with a dual heater system and a new 300 rpm air knife-assisted low-spin dry cycle. The Model UH118 takes wafer cleaning to the next level.



Model UH118

ULTRON SYSTEMS, INC.



Model UH118 Wafer Cleaning System



SPECIFICATIONS

Height: 24"
Width: 29"
Depth: 34"
Weight: 202 lbs.

SERVICE REQUIREMENTS

Vacuum: 25" Hg.
DI/Additive: 2l/min @ 20 psi
N₂/Air: 40l/min @ 50-60 psi
Voltage: 115VAC, 10A

FEATURES

- Large brush system accommodates 300mm wafer or 200mm wafer with frame
- Wafer cleaning with DI water and up to 2 different additives
- Dual heater for faster drying
- Programmable chuck height
- Programmable brush rotation speed
- Programmable wash, rinse, and dry cycles
- Spin dry (@ 300 rpm)

OPTIONS

Floor-standing base



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